

ABSTRACT

Organic electronic device structures are provided, which comprise: (a) a first portion comprising a substrate and an organic electronic device region (e.g., an OLED region) disposed over the substrate; (b) a second portion comprising a cover and a getter region; and (c) a radiation-curable, pressure-sensitive adhesive layer disposed between the first and second portions and adhering the first and second portions to one another. The adhesive layer is disposed over the entire organic electronic device region and over at least a portion of the substrate. Other aspects of the present invention are directed to methods of making the above structures.